

Title (en)

METHOD FOR PRODUCING A MICROSTRUCTURE

Title (de)

VERFAHREN ZUM ERZEUGEN EINER MIKROSTRUKTUR

Title (fr)

PROCÉDÉ DE RÉALISATION D'UNE MICROSTRUCTURE

Publication

**EP 2240330 A2 20101020 (DE)**

Application

**EP 08866269 A 20081217**

Priority

- EP 2008010739 W 20081217
- DE 102007062089 A 20071221

Abstract (en)

[origin: WO2009083146A2] The invention relates to a method for producing a microstructure on a carrier (22), in which a carrier (22) is provided with a relief structure (26, 28) having elevations (26) and depressions (28), and in which the elevations (26) and/or depressions (26) are arranged in the form of the desired microstructure, and an imprint substance (30; 34) is transferred onto the relief structure (26, 28) by means of a printing tool, wherein the viscosity of the imprint substance (30; 34) is chosen in such a way that the imprint substance (30; 34) is transferred selectively either substantially only onto the elevations (26) or substantially only into the depressions (28) of the relief structure.

IPC 8 full level

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CPC (source: EP US)

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Citation (search report)

See references of WO 2009083146A2

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